



# HLT3000

## Two-part, Dispensable Thermal Gap Filler with High Thermal Conductivity

### BENEFIT AND FEATURES

- Modified viscosity and thixotropy properties
- Suitable for dispensing and printing process
- Thin bond line
- Excellent surface wetting
- Proven long term reliability

### OVERVIEW

Honeywell HLT3000 is two-part, dispensable thermal gap filler with low viscosity and good thixotropy properties. The gap filler is silicone based, it is easy to dispense and print after 1:1 mixing. It is formulated to balance thermal performance, phase separation and long term reliability. With its high compressibility, it is designed to minimize thermal resistance at interfaces and suitable for thin bond line applications. The material is available in 200+200cc syringes, 1+1 gallon and 5+5 gallon jars.

### TYPICAL APPLICATIONS

- EV battery package
- Automotive electronics
- Telecommunications
- LED lighting
- Consumer electronics

### STORAGE & USE

- Shelf Life 6 months at 23±2°C

Property	HLT3000	Test Method
Specific Gravity	3.1	ASTM D792
Viscosity (cps@25°C)	100,000-200,000	ASTM D2196 (Brookfield Viscometer, #7 spindle, 10rpm)
Hardness (Shore00)	50	ASTM D2240
Thermal Conductivity (W/m-K)	3.0	ASTM D5470
Dielectric Strength (KV/mm)	>10	ASTM D149
Volume Resistivity(Ω-cm)	>1.0×10 <sup>13</sup>	ASTM D257
BLT(mm)	0.05	-
Cure Schedule	25°C (hr)	18
	120°C (min)	20
Pot Life	25°C (min)	>60
Color	White/Blue	Visual

### Honeywell Electronic Materials

USA: 1-509-252-2102  
 China: 400-840-2233  
 Germany: 49-5137-999-9199  
 Japan: 81-3-6730-7092  
 Korea: 82-2-3483-5076  
 Singapore: 65-6580-3593  
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